

CLAIMS

1. A board for printed wiring comprising:

a substrate;

an adhesive layer of a metal oxide provided on a
5 surface of the substrate; and

an electromagnetic wave absorbing laminate
provided on the adhesive layer, and said electromagnetic
wave absorbing laminate comprising:

(a) a magnetic layer comprising a plurality of
10 magnetic particles having an average particle diameter
of 1 to 150 nm and isolated from each other by an
electrically insulative material; and

(b) an electrically insulative layer;

the magnetic layer and the electrically insulative
15 layer being alternately stacked in a multi-layer
structure having at least two layers.

2. A board for printed wiring as set forth in claim
1, wherein the magnetic particles are composed of at least
one metal selected from the group consisting of Fe, Co
20 and Ni or the oxide of said metal.

3. A board for printed wiring as set forth in claim
1, wherein the magnetic particles are respectively coated
with electrically insulative films to provide a plurality
of composite particles, and said composite particles are
25 bound each other to constitute the magnetic layer.

4. A board for printed wiring as set forth in claim 3, wherein the electrically insulative films are composed of the oxide of at least one metal selected from the group consisting of Si, Al, Ti and Zr, an amine derivative, 5 an alkanethiol derivative or a resin.

5. A board for printed wiring as set forth in claim 3, wherein the electrically insulative films have a covering ratio of 10 to 50 vol% based on the total amount of the composite particles.

10 6. A board for printed wiring as set forth in claim 3, wherein the plurality of composite particles are bound by a binder to constitute the magnetic layer.

7. A board for printed wiring as set forth in claim 1, wherein the adhesive layer is composed of at least 15 a Ti containing metal oxide.

8. A board for printed wiring as set forth in claim 1, wherein the adhesive layer has a thickness of 3 to 150 nm.

9. A board for printed wiring as set forth in claim 20 1, wherein the electrically insulative layer is composed of the oxide of at least one metal selected from the group consisting of Si, Al, Ti and Zr, or a curable resin.

10. A board for printed wiring as set forth in claim 1, wherein the electromagnetic wave absorbing laminate 25 has a complex permeability μ having a real part μ' and

an imaginary part μ'' which satisfy a relationship $\mu' > \mu''$
in a predetermined frequency range within a high frequency
band up to 2GHz.